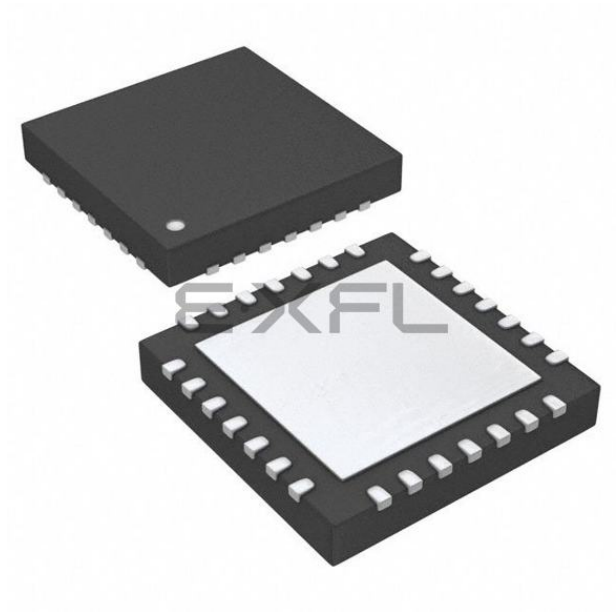

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16km102-e-ml

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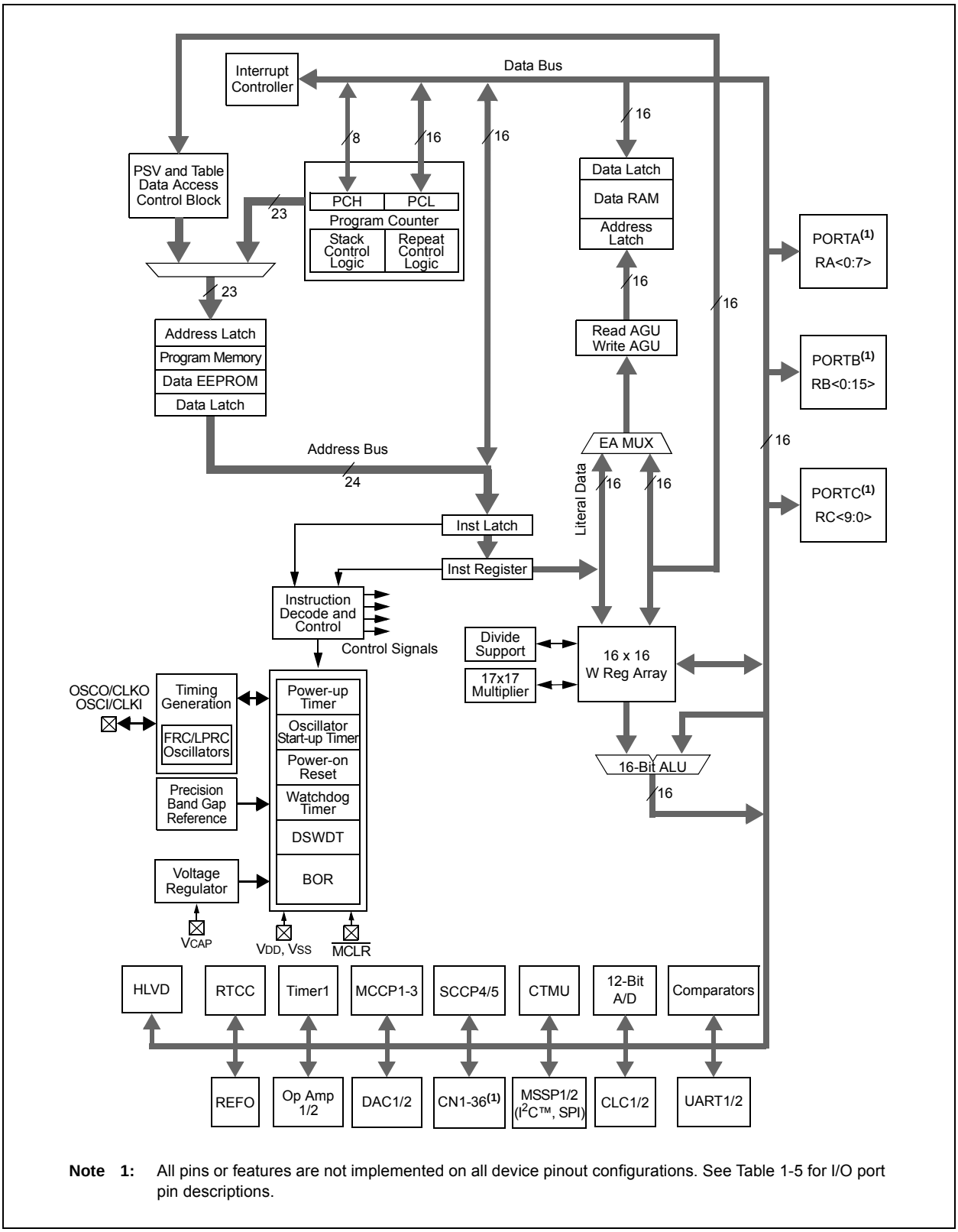
FIGURE 1-1: PIC24FXXXXX FAMILY GENERAL BLOCK DIAGRAMS



Note 1: All pins or features are not implemented on all device pinout configurations. See Table 1-5 for I/O port pin descriptions.

TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
RB9	13	18	15	1	1	13	18	15	1	1	I/O	ST	PORTB Pins
RB10	—	21	18	8	9	—	21	18	8	9	I/O	ST	PORTB Pins
RB11	—	22	19	9	10	—	22	19	9	10	I/O	ST	PORTB Pins
RB12	15	23	20	10	11	15	23	20	10	11	I/O	ST	PORTB Pins
RB13	16	24	21	11	12	16	24	21	11	12	I/O	ST	PORTB Pins
RB14	17	25	22	14	15	17	25	22	14	15	I/O	ST	PORTB Pins
RB15	18	26	23	15	16	18	26	23	15	16	I/O	ST	PORTB Pins
RC0	—	—	—	25	27	—	—	—	25	27	I/O	ST	PORTC Pins
RC1	—	—	—	26	28	—	—	—	26	28	I/O	ST	PORTC Pins
RC2	—	—	—	27	29	—	—	—	27	29	I/O	ST	PORTC Pins
RC3	—	—	—	36	39	—	—	—	36	39	I/O	ST	PORTC Pins
RC4	—	—	—	37	40	—	—	—	37	40	I/O	ST	PORTC Pins
RC5	—	—	—	38	41	—	—	—	38	41	I/O	ST	PORTC Pins
RC6	—	—	—	2	2	—	—	—	2	2	I/O	ST	PORTC Pins
RC7	—	—	—	3	3	—	—	—	3	3	I/O	ST	PORTC Pins
RC8	—	—	—	4	4	—	—	—	4	4	I/O	ST	PORTC Pins
RC9	—	—	—	5	5	—	—	—	5	5	I/O	ST	PORTC Pins
REFO	18	26	23	15	16	18	26	23	15	16	O	—	Reference Clock Output
RTCC	—	25	22	14	15	—	25	22	14	15	O	—	Real-Time Clock/Calendar Output
SCK1	15	22	19	9	10	15	22	19	9	10	I/O	ST	MSSP1 SPI Clock
SDI1	17	21	18	8	9	17	21	18	8	9	I	ST	MSSP1 SPI Data Input
SDO1	16	24	21	11	12	16	24	21	11	12	O	—	MSSP1 SPI Data Output
$\overline{SS1}$	18	26	23	15	16	18	26	23	15	16	I	ST	MSSP1 SPI Slave Select Input
SCK2	—	14	11	38	41	—	14	11	38	41	I/O	ST	MSSP2 SPI Clock
SDI2	—	19	16	36	39	—	19	16	36	39	I	ST	MSSP2 SPI Data Input
SDO2	—	15	12	37	40	—	15	12	37	40	O	—	MSSP2 SPI Data Output
$\overline{SS2}$	—	23	20	35	38	—	23	20	35	38	I	ST	MSSP2 SPI Slave Select Input

Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, I^2C™ = I^2C/SMBus input buffer

TABLE 4-4: ICN REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNPD1	56h	CN15PDE(1,2)	CN14PDE	CN13PDE	CN12PDE	CN11PDE	CN10PDE(2)	CN9PDE(1,2)	—	CN7PDE(1,2)	CN6PDE	CN5PDE	CN4PDE	CN3PDE	CN2PDE	CN1PDE	CN0PDE	0000
CNPD2	58h	CN31PDE(2)	CN30PDE	CN29PDE	CN28PDE(2)	CN27PDE(1,2)	CN26PDE(2)	CN25PDE(2)	CN24PDE(1,2)	CN23PDE	CN22PDE	CN21PDE	CN20PDE(2)	CN19PDE(2)	CN18PDE(2)	CN17PDE(2)	CN16PDE(1,2)	0000
CNPD3	5Ah	—	—	—	—	—	—	—	—	—	—	—	CN36PDE(2)	CN35PDE(2)	CN34PDE(2)	CN33PDE(2)	CN32PDE(2)	0000
CNEN1	62h	CN15IE(1,2)	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE(2)	CN9IE(1,2)	—	CN7IE(1,2)	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	64h	CN31IE(2)	CN30IE	CN29IE	CN28IE(2)	CN27IE(1,2)	CN26IE(2)	CN25IE(2)	CN24IE(1,2)	CN23IE	CN22IE	CN21IE	CN20IE(2)	CN19IE(2)	CN18IE(2)	CN17IE(2)	CN16IE(1,2)	0000
CNEN3	66h	—	—	—	—	—	—	—	—	—	—	—	CN36IE(2)	CN35IE(2)	CN34IE(2)	CN33IE(2)	CN32IE(2)	0000
CNPU1	6Eh	CN15PUE(1,2)	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE(2)	CN9PUE(1,2)	—	CN7PUE(1,2)	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	70h	CN31PUE(2)	CN30PUE	CN29PUE	CN28PUE(2)	CN27PUE(1,2)	CN26PUE(2)	CN25PUE(2)	CN24PUE(1,2)	CN23PUE	CN22PUE	CN21PUE	CN20PUE(2)	CN19PUE(2)	CN18PUE(2)	CN17PUE(2)	CN16PUE(1,2)	0000
CNPU3	72h	—	—	—	—	—	—	—	—	—	—	—	CN36PUE(2)	CN35PUE(2)	CN34PUE(2)	CN33PUE(2)	CN32PUE(2)	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.

Note 1: These bits are available only on 28-pin devices

2: These bits are available only on 44-pin devices

TABLE 4-21: PORTA REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11(4,5)	Bit 10(4,5)	Bit 9(4,5)	Bit 8(4,5)	Bit 7(4)	Bit 6(3)	Bit 5(2)	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	2C0h	—	—	—	—	TRISA11	TRISA10	TRISA9	TRISA8	TRISA7	TRISA6	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	0FDF(1)
PORTA	2C2h	—	—	—	—	RA11	RA10	RA9	RA8	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	2C4h	—	—	—	—	LATA11	LATA10	LATA9	LATA8	LATA7	LATA6	—	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA	2C6h	—	—	—	—	ODA11	ODA10	ODA9	ODA8	ODA7	ODA6	—	ODA4	ODA3	ODA2	ODA1	ODA0	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: Reset value depends on the device type; the PIC24F16KM204 value is shown.
2: These bits are only available when MCLRE (FPOR<7>) = 0.
3: These bits are not implemented in FV devices.
4: These bits are not implemented in 20-pin devices.
5: These bits are not implemented in 28-pin devices.

TABLE 4-22: PORTB REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11(2)	Bit 10(2)	Bit 9	Bit 8	Bit 7	Bit 6(2)	Bit 5(2)	Bit 4	Bit 3(2)	Bit 2	Bit 1	Bit 0	All Resets
TRISB	2C8h	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF(1)
PORTB	2CAh	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	2CCh	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	2CEh	ODB15	ODB14	ODB13	ODB12	ODB11	ODB10	ODB9	ODB8	ODB7	ODB6	ODB5	ODB4	ODB3	ODB2	ODB1	ODB0	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: Reset value depends on the device type; the PIC24F16KM204 value is shown.
2: These bits are not implemented in 20-pin devices.

TABLE 4-23: PORTC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9(2,3)	Bit 8(2,3)	Bit 7(2,3)	Bit 6(2,3)	Bit 5(2,3)	Bit 4(2,3)	Bit 3(2,3)	Bit 2(2,3)	Bit 1(2,3)	Bit 0(2,3)	All Resets
TRISC	2D0h	—	—	—	—	—	—	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	03FF(1)
PORTC	2D2h	—	—	—	—	—	—	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATTC	2D4h	—	—	—	—	—	—	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	2D6h	—	—	—	—	—	—	ODC9	ODC8	ODC7	ODC6	ODC5	ODC4	ODC3	ODC2	ODC1	ODC0	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: Reset value depends on the device type; the PIC24F16KM204 value is shown.
2: These bits are not implemented in 20-pin devices.
3: These bits are not implemented in 28-pin devices.

7.4.2 SOFTWARE ENABLED BOR

When BOREN<1:0> = 01, the BOR can be enabled or disabled by the user in software. This is done with the control bit, SBOREN (RCON<13>). Setting SBOREN enables the BOR to function as previously described. Clearing the SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise, it is read as '0'.

Placing BOR under software control gives the user the additional flexibility of tailoring the application to its environment without having to reprogram the device to change the BOR configuration. It also allows the user to tailor the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when the BOR is under software control, the Brown-out Reset voltage level is still set by the BORV<1:0> Configuration bits; it can not be changed in software.

7.4.3 DETECTING BOR

When BOR is enabled, the BOR bit (RCON<1>) is always reset to '1' on any BOR or POR event. This makes it difficult to determine if a BOR event has occurred just by reading the state of BOR alone. A more reliable method is to simultaneously check the state of both POR and BOR. This assumes that the POR and BOR bits are reset to '0' in the software immediately after any POR event. If the BOR bit is '1' while POR is '0', it can be reliably assumed that a BOR event has occurred.

7.4.4 DISABLING BOR IN SLEEP MODE

When BOREN<1:0> = 10, BOR remains under hardware control and operates as previously described. However, whenever the device enters Sleep mode, BOR is automatically disabled. When the device returns to any other operating mode, BOR is automatically re-enabled.

This mode allows for applications to recover from brown-out situations, while actively executing code, when the device requires BOR protection the most. At the same time, it saves additional power in Sleep mode by eliminating the small incremental BOR current.

Note:	BOR levels differ depending on device type; PIC24FV16KM204 devices are at different levels than those of PIC24F16KM204 devices. See **Section 27.0 "Electrical Characteristics"** for BOR voltage levels.

REGISTER 8-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
NSTDIS	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0
—	—	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14-5 **Unimplemented:** Read as '0'

bit 4 **MATHERR:** Arithmetic Error Trap Status bit
1 = Overflow trap has occurred
0 = Overflow trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

bit 2 **STKERR:** Stack Error Trap Status bit
1 = Stack error trap has occurred
0 = Stack error trap has not occurred

bit 1 **OSCFAIL:** Oscillator Failure Trap Status bit
1 = Oscillator failure trap has occurred
0 = Oscillator failure trap has not occurred

bit 0 **Unimplemented:** Read as '0'

REGISTER 8-5: IFS0: INTERRUPT FLAG STATUS REGISTER 0

R/W-0, HS	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0	U-0	R/W-0, HS
NVMIF	—	AD1IF	U1TXIF	U1RXIF	—	—	CCT2IF
bit 15							bit 8

R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS
CCT1IF	CCP4IF	CCP3IF	—	T1IF	CCP2IF	CCP1IF	INT0IF
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **NVMIF:** NVM Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 14 **Unimplemented:** Read as '0'

bit 13 **AD1IF:** A/D Conversion Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12 **U1TXIF:** UART1 Transmitter Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **U1RXIF:** UART1 Receiver Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10-9 **Unimplemented:** Read as '0'

bit 8 **CCT2IF:** Capture/Compare 2 Timer Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7 **CCT1IF:** Capture/Compare 1 Timer Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **CCP4IF:** Capture/Compare 4 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **CCP3IF:** Capture/Compare 3 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **Unimplemented:** Read as '0'

bit 3 **T1IF:** Timer1 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **CCP2IF:** Capture/Compare 2 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **CCP1IF:** Capture/Compare 1 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **INT0IF:** External Interrupt 0 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 7 **CLKLOCK:** Clock Selection Lock Enable bit
If FSCM is Enabled (FCKSM1 = 1):
1 = Clock and PLL selections are locked
0 = Clock and PLL selections are not locked and may be modified by setting the OSWEN bit
If FSCM is Disabled (FCKSM1 = 0):
Clock and PLL selections are never locked and may be modified by setting the OSWEN bit.

bit 6 **Unimplemented:** Read as '0'

bit 5 **LOCK:** PLL Lock Status bit(2)
1 = PLL module is in lock or PLL module start-up timer is satisfied
0 = PLL module is out of lock, PLL start-up timer is running or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit
1 = FSCM has detected a clock failure
0 = No clock failure has been detected

bit 2 **SOSCDRV**: Secondary Oscillator Drive Strength bit(3)
1 = High-power SOSC circuit is selected
0 = Low/high-power select is done via the SOSCSRC Configuration bit

bit 1 **SOSCEN:** 32 kHz Secondary Oscillator (SOSC) Enable bit
1 = Enables the Secondary Oscillator
0 = Disables the Secondary Oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
1 = Initiates an oscillator switch to the clock source specified by the NOSC<2:0> bits
0 = Oscillator switch is complete

Note 1: Reset values for these bits are determined by the FNOSCx Configuration bits.
2: This bit also resets to '0' during any valid clock switch or whenever a non-PLL Clock mode is selected.
3: When SOSC is selected to run from a digital clock input, rather than an external crystal (SOSCSRC = 0), this bit has no effect.

REGISTER 16-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1) (CONTINUED)

bit 7-0 **CAL<7:0>:** RTC Drift Calibration bits

01111111 = Maximum positive adjustment; adds 508 RTC clock pulses every one minute
.
.
.
00000001 = Minimum positive adjustment; adds 4 RTC clock pulses every one minute
00000000 = No adjustment
11111111 = Minimum negative adjustment; subtracts 4 RTC clock pulses every one minute
.
.
.
10000000 = Maximum negative adjustment; subtracts 512 RTC clock pulses every one minute

Note 1: The RCFGCAL register is only affected by a POR.

2: A write to the RTCEN bit is only allowed when RTCWREN = 1.

3: This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

REGISTER 16-2: RTCPWC: RTCC CONFIGURATION REGISTER 2(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PWCEN	PWCPOL	PWCCPRE	PWCSPRE	RTCCLK1(2)	RTCCLK0(2)	RTCOUT1	RTCOUT0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PWCEN:** Power Control Enable bit
1 = Power control is enabled
0 = Power control is disabled

bit 14 **PWCPOL:** Power Control Polarity bit
1 = Power control output is active-high
0 = Power control output is active-low

bit 13 **PWCCPRE:** Power Control/Stability Prescaler bits
1 = PWC stability window clock is divide-by-2 of source RTCC clock
0 = PWC stability window clock is divide-by-1 of source RTCC clock

bit 12 **PWCSPRE:** Power Control Sample Prescaler bits
1 = PWC sample window clock is divide-by-2 of source RTCC clock
0 = PWC sample window clock is divide-by-1 of source RTCC clock

bit 11-10 **RTCCLK<1:0>:** RTCC Clock Select bits(2)
Determines the source of the internal RTCC clock, which is used for all RTCC timer operations.
00 = External Secondary Oscillator (SOSC)
01 = Internal LPRC Oscillator
10 = External power line source – 50 Hz
11 = External power line source – 60 Hz

bit 9-8 **RTCOUT<1:0>:** RTCC Output Select bits
Determines the source of the RTCC pin output.
00 = RTCC alarm pulse
01 = RTCC seconds clock
10 = RTCC clock
11 = Power control

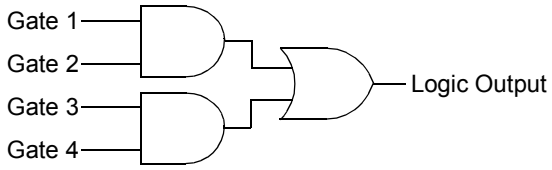
bit 7-0 **Unimplemented:** Read as '0'

Note 1: The RTCPWC register is only affected by a POR.

2: When a new value is written to these register bits, the Seconds Value register should also be written to properly reset the clock prescalers in the RTCC.

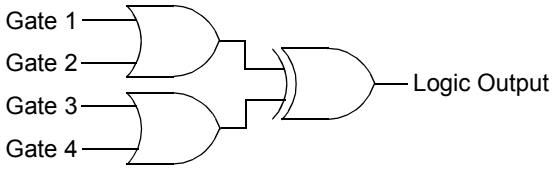
FIGURE 17-2: CLCx LOGIC FUNCTION COMBINATORIAL OPTIONS

AND – OR



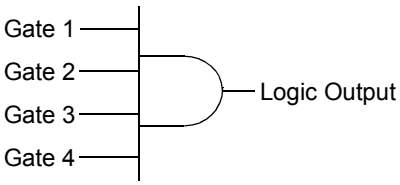
MODE<2:0> = 000

OR – XOR



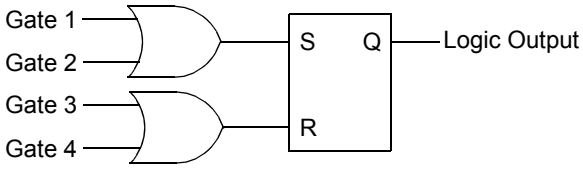
MODE<2:0> = 001

4-Input AND



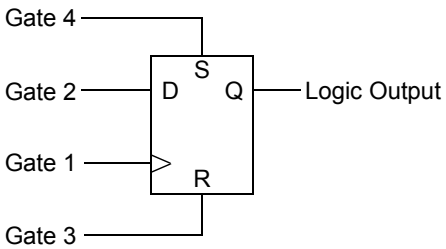
MODE<2:0> = 010

S-R Latch



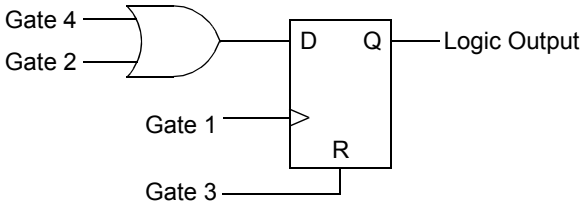
MODE<2:0> = 011

1-Input D Flip-Flop with S and R



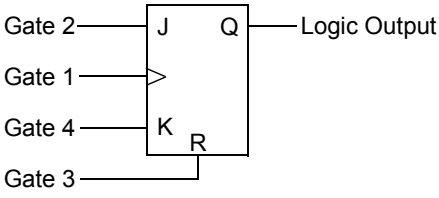
MODE<2:0> = 100

2-Input D Flip-Flop with R



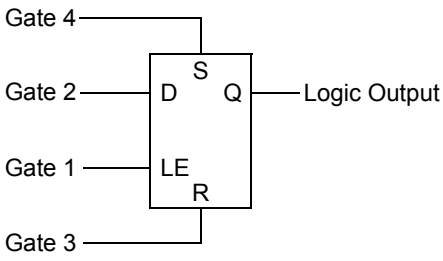
MODE<2:0> = 101

J-K Flip-Flop with R



MODE<2:0> = 110

1-Input Transparent Latch with S and R



MODE<2:0> = 111

REGISTER 17-4: CLCxGLSL: CLCx GATE LOGIC INPUT SELECT LOW REGISTER (CONTINUED)

bit 3 **G1D2T:** Gate 1 Data Source 2 True Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 1
0 = The Data Source 2 inverted signal is disabled for Gate 1

bit 2 **G1D2N:** Gate 1 Data Source 2 Negated Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 1
0 = The Data Source 2 inverted signal is disabled for Gate 1

bit 1 **G1D1T:** Gate 1 Data Source 1 True Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 1
0 = The Data Source 1 inverted signal is disabled for Gate 1

bit 0 **G1D1N:** Gate 1 Data Source 1 Negated Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 1
0 = The Data Source 1 inverted signal is disabled for Gate 1

19.4 Buffer Data Formats

The A/D conversions are fully differential 12-bit values when MODE12 = 1 (AD1CON1<10>) and 10-bit values when MODE12 = 0. When absolute fractional or absolute integer formats are used, the results are 12 or 10 bits wide, respectively. When signed decimal formatting is used, the conversion also includes a Sign bit, making 12-bit conversions 13 bits wide and 10-bit conversions 11 bits wide. The signed decimal format yields 12-bit and 10-bit values, respectively. The Sign bit (bit 12 or bit 10) is sign-extended to fill the buffer. The FORM<1:0> bits (AD1CON1<9:8>) select the format. Figure 19-4 and Figure 19-5 show the data output formats that can be selected. Table 19-1 through Table 19-4 show the numerical equivalents for the various conversion result codes.

FIGURE 19-4: A/D OUTPUT DATA FORMATS (12-BIT)

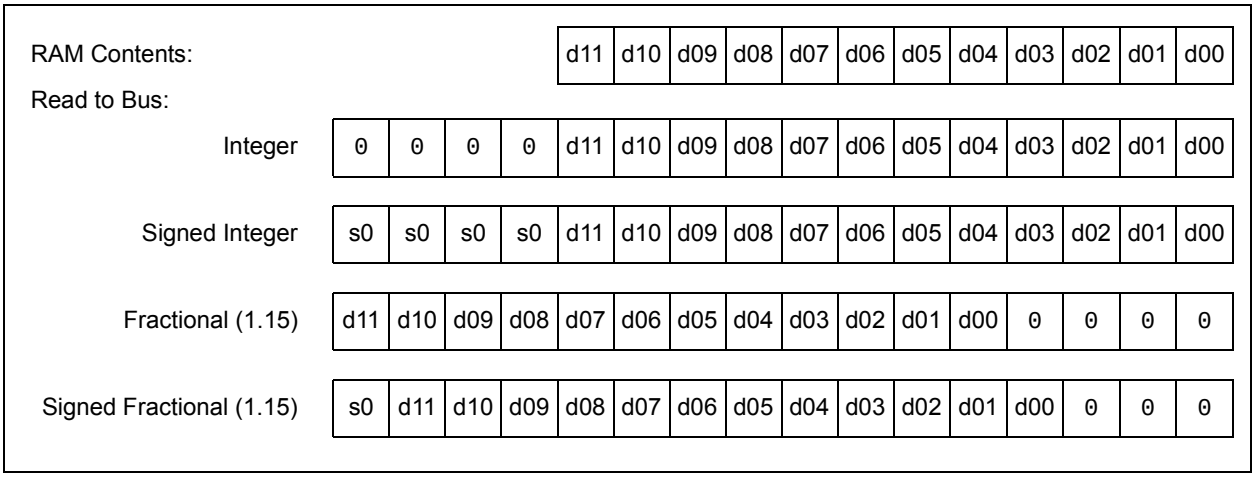


TABLE 19-1: NUMERICAL EQUIVALENTS OF VARIOUS RESULT CODES: 12-BIT INTEGER FORMATS

VIN/VREF	12-Bit Differential Output Code (13-bit result)	16-Bit Integer Format/ Equivalent Decimal Value		16-Bit Signed Integer Format/ Equivalent Decimal Value	
+4095/4096	0 1111 1111 1111	0000 1111 1111 1111	+4095	0000 1111 1111 1111	+4095
+4094/4096	0 1111 1111 1110	0000 1111 1111 1110	+4094	0000 1111 1111 1110	+4094
• • •					
+1/4096	0 1000 0000 0001	0000 0000 0000 0001	+1	0000 0000 0000 0001	+1
0/4096	0 0000 0000 0000	0000 0000 0000 0000	0	0000 0000 0000 0000	0
-1/4096	1 0111 1111 1111	0000 0000 0000 0000	0	1111 1111 1111 1111	-1
• • •					
-4095/4096	1 0000 0000 0001	0000 0000 0000 0000	0	1111 0000 0000 0001	-4095
-4096/4096	1 0000 0000 0000	0000 0000 0000 0000	0	1111 0000 0000 0000	-4096

NOTES:

REGISTER 20-1: DACxCON: DACx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
DACEN	—	DACSIDL	DACSLP	DACFM	—	SRDIS	DACTRIG
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DACOE	DACTSEL4	DACTSEL3	DACTSEL2	DACTSEL1	DACTSEL0	DACREF1	DACREF0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **DACEN:** DACx Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **DACSIDL:** DACx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **DACSLP:** DACx Enable Peripheral During Sleep bit
1 = DACx continues to output the most recent value of DACxDAT during Sleep mode
0 = DACx is powered down in Sleep mode; DACxOUT pin is controlled by the TRISx and LATx bits

bit 11 **DACFM:** DACx Data Format Select bit
1 = Data is left justified (data stored in DACxDAT<15:8>)
0 = Data is right justified (data stored in DACxDAT<7:0>)

bit 10 **Unimplemented:** Read as ‘0’

bit 9 **SRDIS:** Soft Reset Disable bit
1 = DACxCON and DACxDAT SFRs reset only on a POR or BOR Reset
0 = DACxCON and DACxDAT SFRs reset on any type of device Reset

bit 8 **DACTRIG:** DACx Trigger Input Enable bit
1 = Analog output value updates when the selected (by DACTSEL<4:0>) event occurs
0 = Analog output value updates as soon as DACxDAT is written (DAC Trigger is ignored)

bit 7 **DACOE:** DACx Output Enable bit
1 = DACx output pin is enabled and driven on the DACxOUT pin
0 = DACx output pin is disabled, DACx output is available internally to other peripherals only

Note 1: BGBUF1 voltage is configured by BUFREF<1:0> (BUFCON0<1:0>).

25.2 On-Chip Voltage Regulator

All of the PIC24FXXXXX family devices power their core digital logic at a nominal 3.0V. This may create an issue for designs that are required to operate at a higher typical voltage, as high as 5.0V. To simplify system design, all devices in the "FV" family incorporate an on-chip regulator that allows the device core to run at 3.0V, while the I/O is powered by VDD at a higher voltage.

The regulator is always enabled and provides power to the core from the other VDD pins. A low-ESR capacitor (such as ceramic) must be connected to the VCAP pin (Figure 25-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 27.1 "DC Characteristics"** and discussed in detail in **Section 2.0 "Guidelines for Getting Started with 16-Bit Microcontrollers"**.

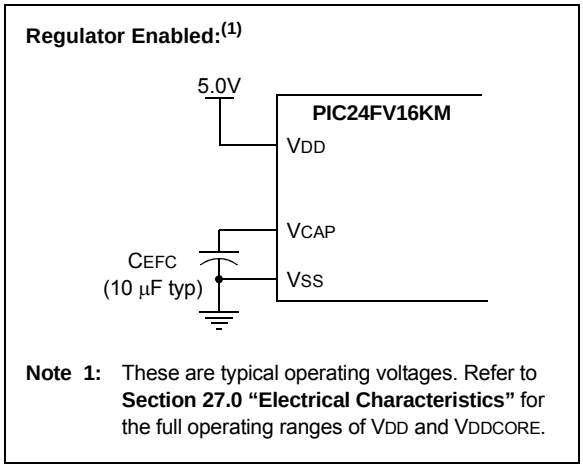
In all of the "F" family of devices, the regulator is disabled. Instead, the core logic is directly powered from VDD. "F" devices operate at a lower range of VDD voltage, from 1.8V-3.6V.

25.2.1 VOLTAGE REGULATOR TRACKING MODE AND LOW-VOLTAGE DETECTION

For all PIC24FXXXXX devices, the on-chip regulator provides a constant voltage of 3.0V nominal to the digital core logic. The regulator can provide this level from a VDD of about 3.2V, all the way up to the device's VDDMAX. It does not have the capability to boost VDD levels below 3.2V. In order to prevent "brown out" conditions when the voltage drops too low for the regulator, the regulator enters Tracking mode. In Tracking mode, the regulator output follows VDD with a typical voltage drop of 150 mV.

When the device enters Tracking mode, it is no longer possible to operate at full speed. To provide information about when the device enters Tracking mode, the on-chip High/Low-Voltage Detect (HLVD) module can be used. The HLVD trip point should be configured so that if VDD drops close to the minimum voltage for the operating frequency of the device, the HLVD Interrupt Flag, HLVDIF (IFS4<8>), will occur. This can be used to generate an interrupt and put the application into a low-power operational mode or trigger an orderly shutdown. Refer to **Section 27.1 "DC Characteristics"** for the specifications detailing the maximum operating speed based on the applied VDD voltage.

FIGURE 25-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 27.0 "Electrical Characteristics"** for the full operating ranges of VDD and VDDCORE.

25.2.2 VOLTAGE REGULATOR START-UP TIME

For PIC24FXXXXX family devices, it takes a short time, designated as TPM, for the regulator to generate a stable output. During this time, code execution is disabled. TPM is applied every time the device resumes operation after any power-down, including Sleep mode. TPM is specified in **Section 27.2 "AC Characteristics and Timing Parameters"**.

25.3 Watchdog Timer (WDT)

For the PIC24FXXXXX family of devices, the WDT is driven by the LPRC Oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 31 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the FWPSA Configuration bit. With a 31 kHz input, the prescaler yields a nominal WDT Time-out period (TWDT) of 1 ms in 5-bit mode or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the Configuration bits, WDTPS<3:0> (FWDT<3:0>), which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler time-out periods, ranges from 1 ms to 131 seconds can be achieved.

TABLE 27-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 27-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 20-Pin PDIP	θ_{JA}	62.4	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SSOP	θ_{JA}	108	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SOIC	θ_{JA}	75	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	80.2	—	°C/W	**1**
Package Thermal Resistance, 20-Pin QFN	θ_{JA}	43	—	°C/W	**1**
Package Thermal Resistance, 28-Pin QFN	θ_{JA}	32	—	°C/W	**1**
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29	—	°C/W	**1**
Package Thermal Resistance, 44-Pin TQFP	θ_{JA}	40	—	°C/W	**1**
Package Thermal Resistance, 48-Pin UQFN	θ_{JA}	41	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-$_{JA}$ (θ_{JA}) numbers are achieved by package simulations.

TABLE 27-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX)** **2.0V to 5.5V (PIC24FV16KMXXX)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DC10	V_{DD}	**Supply Voltage**	1.8	—	3.6	V	For PIC24F devices
			2.0	—	5.5	V	For PIC24FV devices
DC12	V_{DR}	**RAM Data Retention Voltage(2)**	1.6	—	—	V	For PIC24F devices
			1.8	—	—	V	For PIC24FV devices
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	V_{SS}	—	0.7	V	
DC17	SV_{DD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 0.1s 0-2.5V in 60 ms

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This is the limit to which V_{DD} can be lowered without losing RAM data.

TABLE 27-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**	
	VOL	**Output Low Voltage**						
DO10		All I/O Pins	—	—	0.4	V	IOL = 8.0 mA	VDD = 4.5V
			—	—	0.4	V	IOL = 4.0 mA	VDD = 3.6V
			—	—	0.4	V	IOL = 3.5 mA	VDD = 2.0V
DO16		OSC2/CLKO	—	—	0.4	V	IOL = 2.0 mA	VDD = 4.5V
			—	—	0.4	V	IOL = 1.2 mA	VDD = 3.6V
			—	—	0.4	V	IOL = 0.4 mA	VDD = 2.0V
	VOH	**Output High Voltage**						
DO20		All I/O Pins	3.8	—	—	V	IOH = -3.5 mA	VDD = 4.5V
			3	—	—	V	IOH = -3.0 mA	VDD = 3.6V
			1.6	—	—	V	IOH = -1.0 mA	VDD = 2.0V
DO26		OSC2/CLKO	3.8	—	—	V	IOH = -2.0 mA	VDD = 4.5V
			3	—	—	V	IOH = -1.0 mA	VDD = 3.6V
			1.6	—	—	V	IOH = -0.5 mA	VDD = 2.0V

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 27-11: DC CHARACTERISTICS: PROGRAM MEMORY

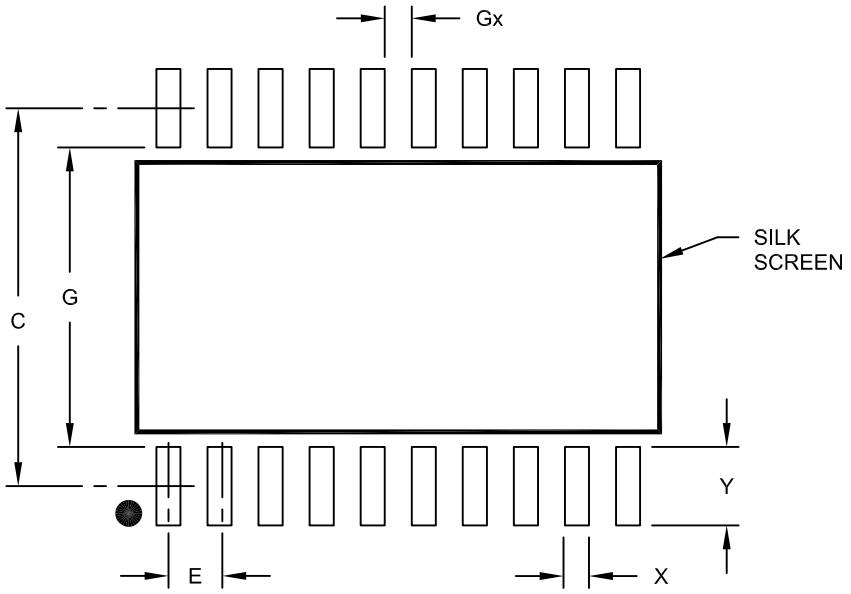
DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000(2)	—	—	E/W	
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D133A	TIW	Self-Timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current During Programming	—	10	—	mA	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: Self-write and block erase.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X20)	X			0.60
Contact Pad Length (X20)	Y			1.95
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.45		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2094A